

IN THE SPECIFICATION

Please amend the specification as follows;

In the section Brief Description of the Drawings replace paragraphs 3-4 with the following:

-- Fig. 4a is a partially sectioned view according to an embodiment of the present invention;

Fig. 4b 4a is a partially sectioned view according to another embodiment of the present invention;--

IN THE CLAIMS:

Please enter the following amended claims:

1. (currently amended) An apparatus for plasma processing of a wafer, the wafer being disposed on a wafer holder during processing said process, the apparatus comprising:
an annular structure including an embedded magnet, the structure concentric with the wafer holder, the embedded magnet generating a magnetic field for deflecting charged particles incident on the structure and reducing plasma density in selected regions during plasma etching, thereby preventing damage to the structure by said particles and eliminating plasma from being present at edges of the wafer.
2. (original) An apparatus according to claim 1, wherein the magnet comprises a magnetic material embedded in said structure.
3. (original) An apparatus according to claim 1, wherein said annular structure is characterized as a ring, the ring having a groove formed therein, and the magnet is disposed in the groove.